

**INSERT FOR TESTING A MICROELECTRONIC DEVICE
HAVING A PLURALITY OF OUTWARDLY-PROJECTING-CONTACTS
AND METHOD OF MAKING THE SAME**

Abstract

An insert is provided for testing a chip-scale-packaged microelectronic device having an encapsulant-protrusion and a ball-grid-array of outwardly-projecting contacts. The insert comprises a substrate of mono-crystalline silicon. Walls of the substrate define a plurality of pockets that are configured to receive and contact the outwardly-projecting contacts of the microelectronic device. Additional walls of the substrate define a recess disposed amongst the plurality of pockets. The recess has a width greater than the widths of any of the pockets. Additionally, the recess comprises a perimeter greater than that of the encapsulant-protrusion of the chip-scale-packaged microelectronic device, and a depth operative to clear the encapsulant-protrusion when the chip-scale package is seated upon the insert.

09916621-072701